

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier Nexperia B.V.		User Part Number PMEG2005EPK-Q					
Nexperia DHAM Schottky							
MCD package							
Test Conditions	Duration	# Lots	# Quantity	# Rejects			
	TEST						
	Pre- and Post-Stress						
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
		JESD22-A113					
		Bake Tamb = 125 °C	24 hours				
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours				
# A1	Preconditioning	Reflow soldering	3 cycles	208	9760	0	
		MIL-STD-750-1					
	HTRB	M1038 Method A					
	High Temperature Reverse	Tj = Tjmax, $Vr = 100%$ of max. datasheet					
# B1	Bias	reverse voltage <sup>[1]</sup>	1000 hours	206	9320	0	
	TC	JESD22-A104					
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	53	2400	0	
	UHAST	JESD22-A118					
# A3 <b>or</b>	Unbiased HAST	Tamb = 130 °C, RH = 85 %		53	2400	0	
# A3 <b>01</b>	Olibiased FIAST	· · · · · · · · · · · · · · · · · · ·	- 96 hours				
	AC	JESD22-A102					
# AO -II	AC Autoclave	Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)					
# A3 alt	Autociave	Pressure = 203 kPa (29.7 psia)					
	H3TRB	JESD22-A101					
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of					
# A2 alt		rated reverse voltage <sup>[1], [2]</sup>	1000 hours	53	2400	0	
, , , L UIL	peratare recreise blus	MIL-STD-750 Method 1037	1000 110015	33	2 100		
	IOL	ton = toff, devices powered to insure $\Delta T_i$ =					
# A5	Intermittent Operating Life		1000 hours	49	2560	0	
5	E	222 232 2900 27000	2000 110013	. ,	2300		
	RSH	JESD22-A111					
# C8	Resistance to Solder Heat		10 s	n.a.	n.a.	n.a.	
50	SD		-50				
# C10	Solderability	J-STD-002		37	1110	0	
	20.acrubincy	7 0.5 002		J1	1110	·	

<sup>[1]</sup> The physical limitations of Schottky diodes have to be considered (thermal runaway).

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

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<sup>[2]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.